

Title (en)

WALL OR FLOOR COVERING COMPOSED OF SEPARATE CERAMIC PANELS

Publication

**EP 0296521 A3 19890531 (DE)**

Application

**EP 88109787 A 19880620**

Priority

DE 3720598 A 19870622

Abstract (en)

[origin: JPS6466358A] PURPOSE: To stabilize leak resistance by a method wherein a voltage applied on a tile-form element made of ceramic having conductivity is dispersed through a conductive means laid on the side of the tile-form element or a tile surface. CONSTITUTION: A conductive tile 1 is electrically connected to a conduction means 4 through a side 3, a joint between tiles is filled with a joint filling material 7, the means 4 is extended to the end of a floor covering, and grounded through, for example, a piezoelectric terminal. Further, when a tile element 1 has a surface on which conductive glaze is applied, the conductive glaze is extended to the side 3 of the element 1 and brought into contact with the means 4. By selecting the number of contacts and the length of each element 1, leakage value is controlled and the same load dispersion capacity is provided by the element 1 having the same resistance value. This constitution prevents the occurrence of instability and a change of leakage resistance due to deterioration with the lapse of time.

IPC 1-7

**E04F 15/02**; H05F 3/02

IPC 8 full level

**E04F 15/18** (2006.01); **E04F 13/14** (2006.01); **E04F 15/02** (2006.01); **H05F 3/02** (2006.01)

CPC (source: EP US)

**E04F 15/02** (2013.01 - EP US)

Citation (search report)

- [X] FR 2204097 A1 19740517 - SOLVAY [BE]
- [AD] EP 0211284 A2 19870225 - BUCHTAL GMBH [DE]
- [A] CH 519071 A 19720215 - KELLER & CO AG [CH]
- [A] FR 2189980 A1 19740125 - DYNAMIT NOBEL AG [DE]
- [A] US 4308568 A 19811229 - WHEWELL BRUCE R
- [A] FR 1297904 A 19620706 - HIPPOLYTE BOULENGER ET CIE

Designated contracting state (EPC)

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DOCDB simple family (publication)

**EP 0296521 A2 19881228**; **EP 0296521 A3 19890531**; **EP 0296521 B1 19920401**; DE 3720598 A1 19890105; DE 3869671 D1 19920507; JP S6466358 A 19890313; US 4870795 A 19891003

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